

## Thermal Conductive Board

### Product Description

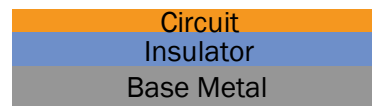
Thermal Conductive Board (TCB), or Insulated Metal Substrate (IMS), provides the advantages of high thermal conductivity, reliability, and thermal resistance. TCB is a sandwich structure, which includes layers of copper foil, insulator, and base metal. The insulator is made by a unique polymer composite that combine epoxy resin and high thermal conductivity filler, and the thermal conductivity is about 5 times higher than the traditional epoxy filled glass fiber system.

### Features

- Excellent thermal conductivity
- Customized substrate structure available
- Excellent solder resistance
- RoHS Complaint
- Excellent reliability
- Over 15 Patents

### Specifications

Characteristics	TCB-4
Panel Size [mm]	405 x 510, 405 x 610
Base Metal [mm]	0.2, 1.0, 1.5, 2.0, or etc.
Dielectric Layer thickness [ $\mu\text{m}$ ]	100, 150
Circuit [oz]	1, 2, 3, or etc.



### General Properties

Characteristics	TCB-4	Test Method
Thermal conductivity [W/m-K]	4	TO-220
Flammability	V-0	94
Break down voltage [AC KV/mm]	50	JIS C 2110
Peeling strength [N/cm]	19	JIS C 6481
Solder heat resistance, 260°C [mins]	>60	
Thermal resistance, TMA, T260 [mins]	>60	IPC-TM-650 2.4.24.1
Glass transition temperature [°C]	140	IPC-TM-650 2.4.25